



## ATTENTION

OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

Part Number: L-7676CQBC-G

Blue

## Features

- Super flux output.
- Design for high current operation.
- Outstanding material efficiency.
- Reliable and rugged.
- RoHS compliant.

### Description

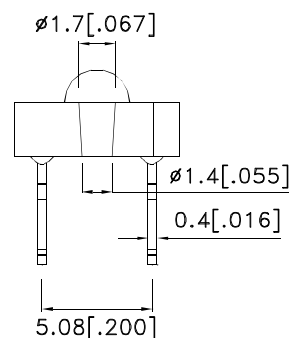
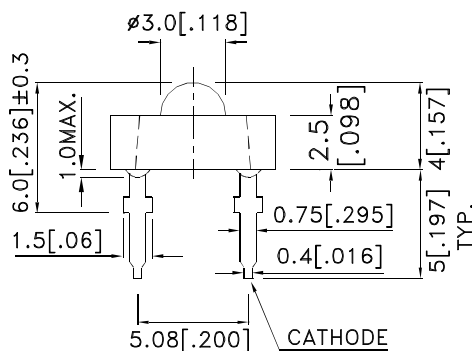
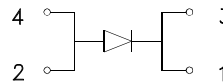
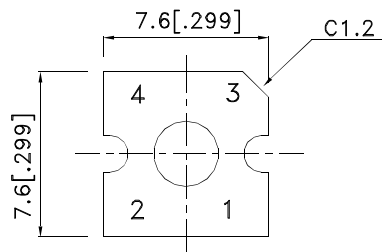
The Blue source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

## Package Dimensions



Notes:

- Notes:
1. All dimensions are in millimeters (inches).
  2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
  3. Lead spacing is measured where the leads emerge from the package.
  4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.





## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
L-7676CQBC-G	Blue (InGaN)	Water Clear	400	780	70°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.
3. Drive current between 10mA and 30mA are recommended for long term performance.
4. Operation at current below 10mA is not recommended.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Blue	461		nm	IF=20mA
λD [1]	Dominant Wavelength	Blue	465		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Blue	25		nm	IF=20mA
C	Capacitance	Blue	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Blue	3.3	4	V	IF=20mA
IR	Reverse Current	Blue		50	uA	VR = 5V

Notes:

- 1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

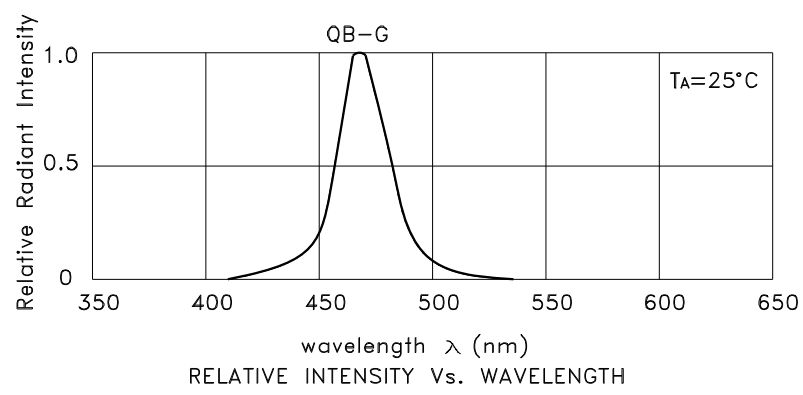
## Absolute Maximum Ratings at TA=25°C

Parameter	Blue	Units
Power dissipation	120	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

Notes:

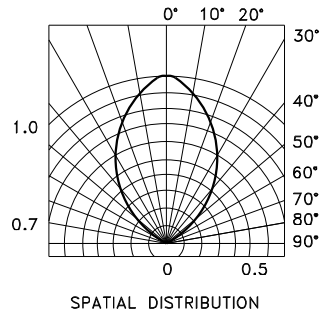
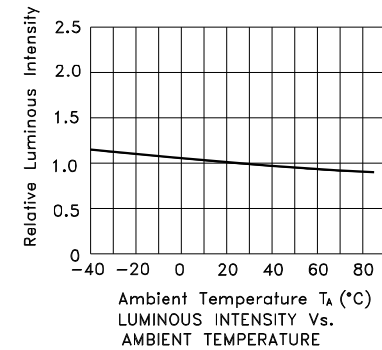
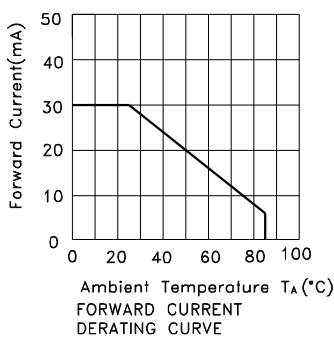
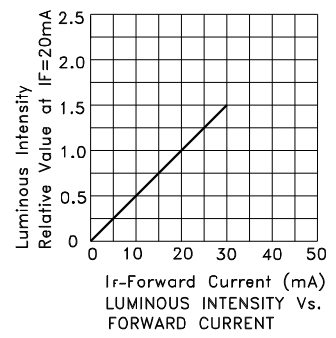
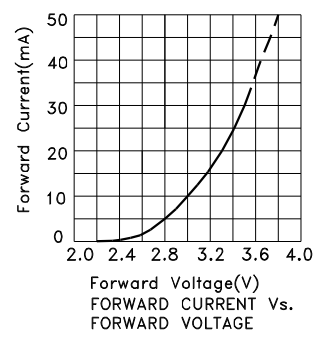
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.





Blue

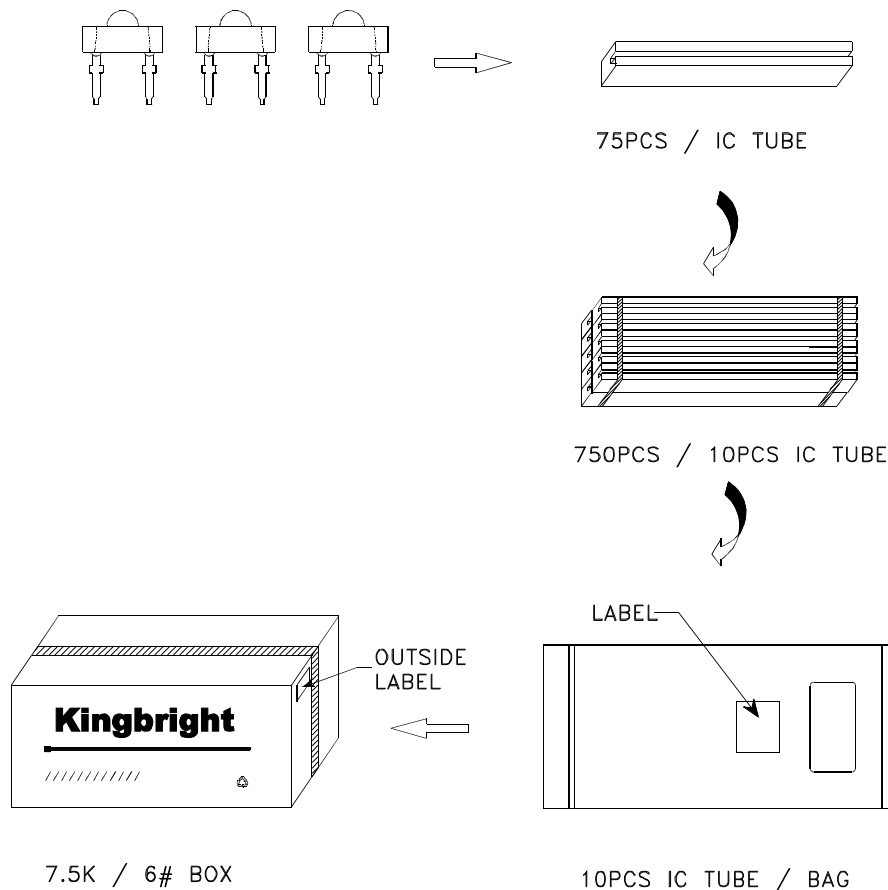
L-7676CQBC-G






## PACKING & LABEL SPECIFICATIONS

L-7676CQBC-G



<b>Kingbright</b>	
P/NO: L-7676Cxxx	
QTY: 750 pcs	Q.C. <div>Q C XX XX XXXX PASSED</div>
S/N: XXXX	
CODE: XXX	
LOT NO:	
 XXXXXXXXXX	
RoHS Compliant	



## LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)

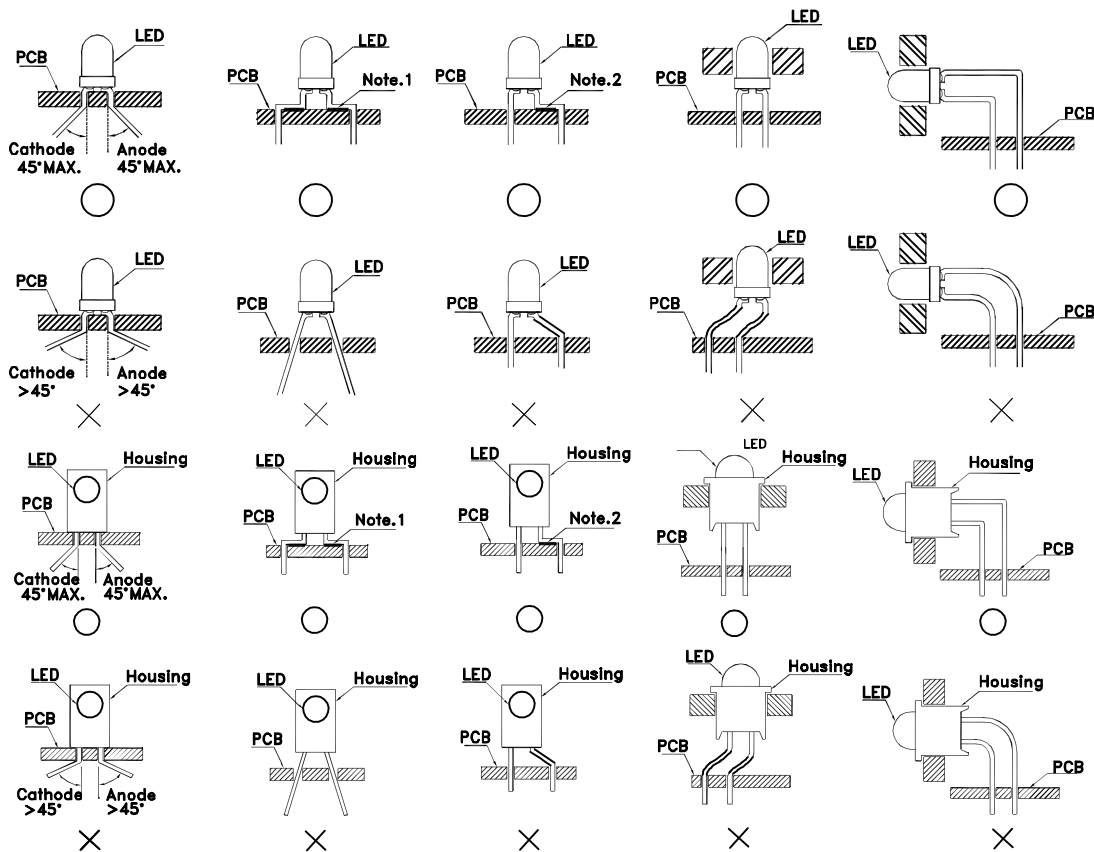


Fig.1

- “○” Correct mounting method “X” Incorrect mounting method  
 Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.
- When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig. 2)
  - Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

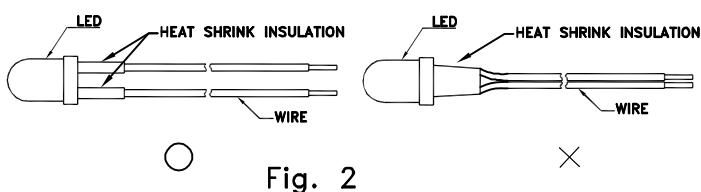


Fig. 2

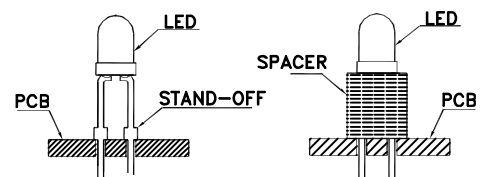


Fig. 3

Fig. 4



## LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)

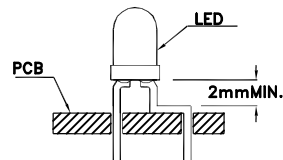


Fig. 5

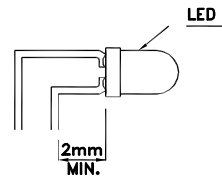


Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)
6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.

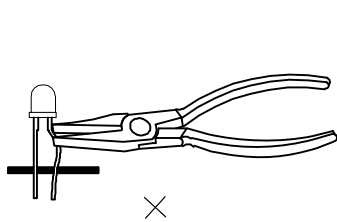


Fig. 7

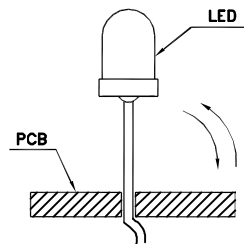


Fig. 8

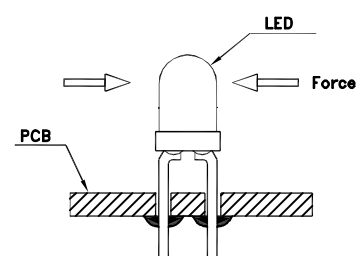


Fig. 9

7. No stress shall be applied on the LED during soldering to prevent damage.

